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### 3 Charac eri ic

Forward c rren	If	30	mA
Re er e ol age	Vr	5	V
Po er di ipa ion	Pd	110	mW
Opera ing empera re range	Top	-25 +80	C
S orage empera re range	T g	-30 +80	C
Peak p l ing c rren 1/8 d f=1KH	Ifp	125	mA

Wa eleng h a peak emi ion	If=20mA	peak	620	630	635	nm
Spec ral half band id h	If=20mA			10		
For ard ol age	If=20mA	Vf	1.8	2.0	2.4	V
L mino in en i	If=20mA	I	1300	1650	2000	mcd



Viewing angle at 50% IV	If=10mA	--	120	--	Deg
Reverse current	Vr=5V	Ir	--	5	A
Useful life	-	IF=20mA	100000		H

Typical Electrical/Optical Characteristics Curve  
(Ta=25 Unless Otherwise Noted)

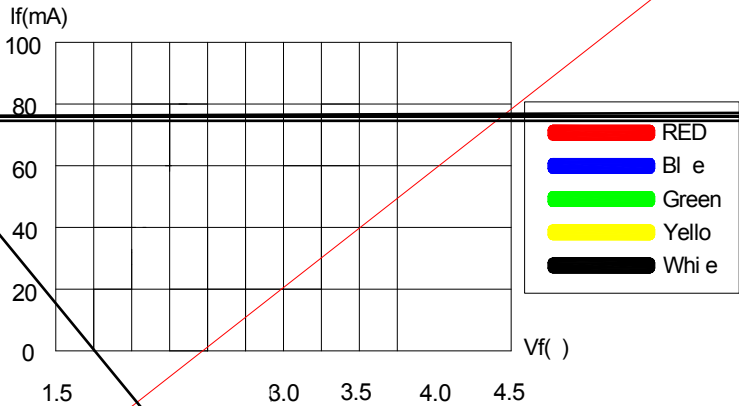


Fig.1 Forward Current vs Forward Voltage

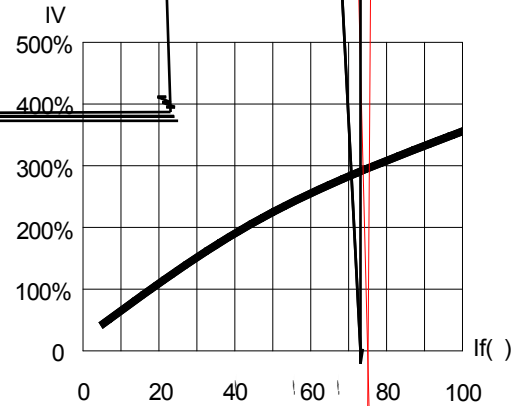


Fig.2 Relative Luminous Intensity vs Forward Voltage

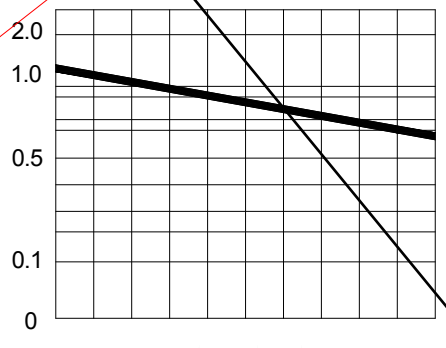


Fig.3 Relative Luminous Intensity vs Ambient Temperature

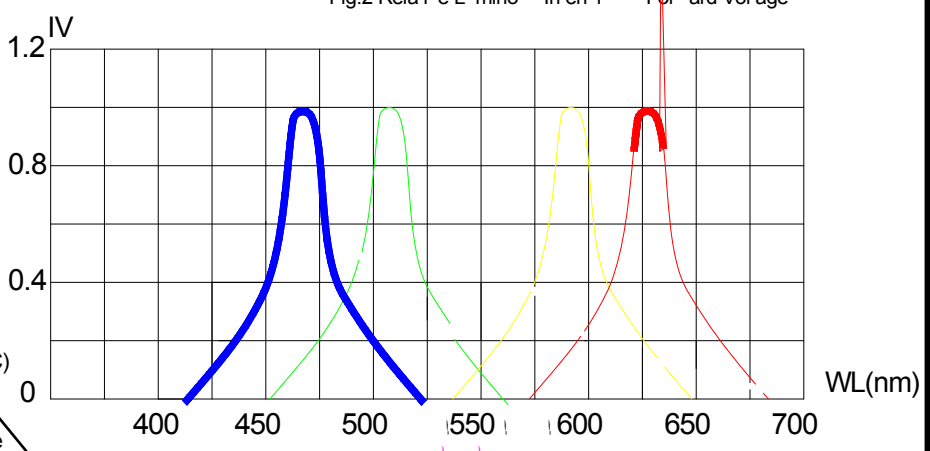


Fig.4 Relative Luminous Intensity vs Wavelength

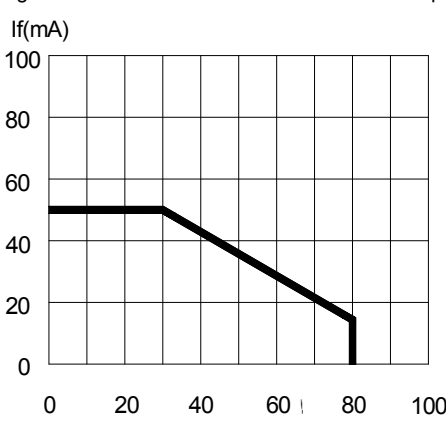
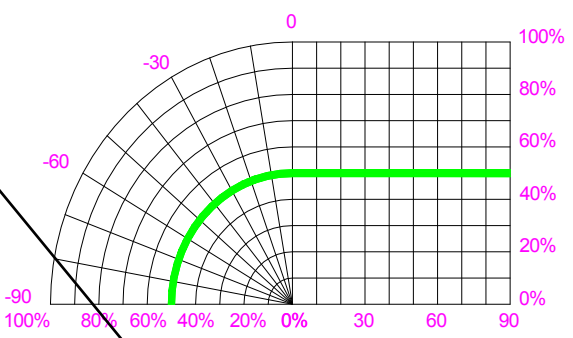


Fig.5 Maximum Forward Current vs Ambient Temperature

- █ RED
- █ Blue
- █ Green
- █ Yellow
- █ White

Directivity Characteristics





1	Tin-plated	Temp 260 ± 5	5 sec.	76 PCS	0/1
2	Back & forth under high & low temperature	High emp. +85 30min to 5min to -55 30min	50 bo	76 PCS	0/1
3	Heating	High emp. +100 30min To 10 sec to -10 30min	50 bo	76 PCS	0/1
4	High storage emp.	Temperature 100	1000 Hr.	76 PCS	0/1
5	Low storage emp.	-55	1000 Hr.	76 PCS	0/1
6	Life span	VF=1.9V IF=20mA	1000 Hr.	76 PCS	0/1
7	Temperature high emp. & high humidity	85 ± 2/85%RH	1000 Hr.	76 PCS	0/1

i Iron Soldering: The Iron (max 30W) end temperature less than 300 °C, soldering time 3 seconds, soldering position minimum 2mm from body.

ii Dip Soldering: Max temperature is 260 °C, time 5s, the position is minimum 2mm from body.

i Bracket must be bent only if 2mm from colloid.

ii Bracket mold must be finished by fire or professional.

iii Bracket mold must be finished before soldering.

i Bracket mold holder are connected between the pin, the distance gap of lead and the circuit board.

i. The holder be placed in order of all the devices in case of wrong polarity. The device can be closed on the heat component working condition can replace the limit.

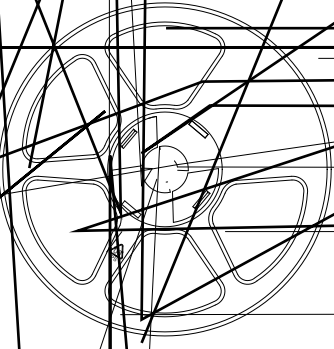
ii. The holder no assemble LED when the lead are deformed.

iii. When decide on assemble in hole, accurately according to the size of hole and hole distance of the line base

i. Storage and handling

i. The holder avoid any kind of quake or force on LED, before the soldering temperature return normal.

The holder be careful. When clean the body with chemical. Some chemical may bring damage to the surface, and bring color fading, such as, Trichloroethylene, Acetone. Should be handled properly, dip for no more than 3 minutes under the normal temperature



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